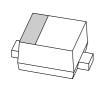
Product data sheet



BA891 Band-switching diode Rev 04 – 8 January 2008

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NXP Semiconductors



Product specification

Band-switching diode

FEATURES

- Ultra small plastic SMD package
- Low diode capacitance: max. 1.05 pF
- Low diode forward resistance: max. 0.7 Ω
- Small inductance.

APPLICATIONS

- · Low loss band-switching in VHF television tuners
- Surface mount band-switching circuits.

DESCRIPTION

The BA891 is a planar high performance band-switching diode in the ultra small SOD523 SMD plastic package.

MARKING

TYPE NUMBER	MARKING CODE		
BA891	7		

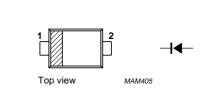
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	35	V
I _F	continuous forward current		_	100	mA
P _{tot}	total power dissipation	T _s = 90 °C	-	715	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



The marking band indicates the cathode.

Fig.1 Simplified outline (SOD523) and symbol.

BA891

Band-switching diode

BA891

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	85	K/W

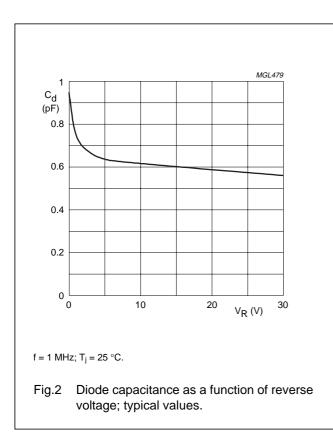
CHARACTERISTICS

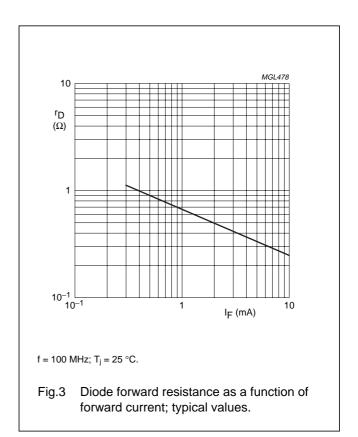
 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 10 mA	-	1	V
I _R	reverse current	V _R = 30 V	-	20	nA
C _d	diode capacitance	f = 1 MHz; note 1; see Fig.2			
		V _R = 1 V	0.8	1.05	pF
		$V_R = 3 V$	0.65	0.9	pF
r _D	diode forward resistance	f = 100 MHz; note 1; see Fig.3			
		$I_F = 3 \text{ mA}$	0.42	0.7	Ω
		I _F = 10 mA	0.28	0.5	Ω
L _S	series inductance		0.6	_	nH

Note

1. Guaranteed on AQL basis; inspection level S4, AQL 1.0.

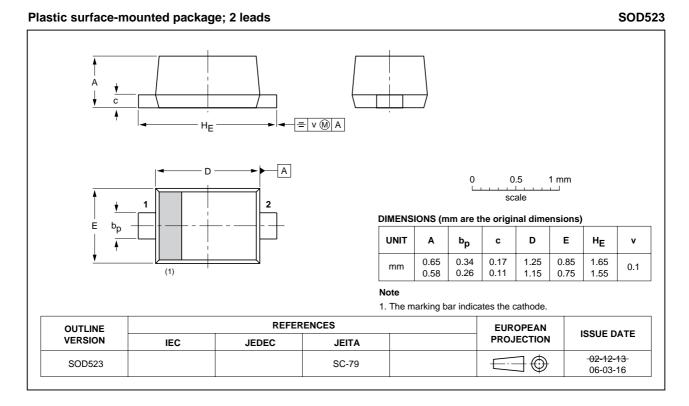




Band-switching diode

BA891

PACKAGE OUTLINE



Legal information

Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Revision history

Release date	Data sheet status	Change notice	Supersedes
20080108	Product data sheet	-	BA891_3
 Package ou 	tline on page 4 changed		
20020125	Product specification	-	BA891_2
19980831	Product specification	-	BA891_1
19980818	Product specification	-	-
	20080108 • Package ou 20020125 19980831	20080108Product data sheet• Package outline on page 4 changed20020125Product specification19980831Product specification	20080108Product data sheet-• Package outline on page 4 changed20020125Product specification19980831Product specification

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Date of release: 8 January 2008 Document identifier: BA891_N_4

